# MBRM130LT1G, NRVBM130LT1G, MBRM130LT3G, NRVBM130LT3G

# Surface Mount Schottky Power Rectifier

## POWERMITE®
## Power Surface Mount Package

The SchottkyPOWERMITE® employs the Schottky Barrier principle with a barrier metal and epitaxial construction that produces optimal forward voltage drop−reverse current tradeoff. The advanced packaging techniques provide for a highly efficient micro miniature, space saving surface mount Rectifier. With its unique heatsink design, thePOWERMITE® has the same thermal performance as the SMA while being 50% smaller in footprint area, and delivering one of the lowest height profiles, < 1.1 mm in the industry. Because of its small size, it is ideal for use in portable and battery powered products such as cellular and cordless phones, chargers, notebook computers, printers, PDAs and PCMCIA cards. Typical applications are AC−DC and DC−DC converters, reverse battery protection, and "ORing" of multiple supply voltages and any other application where performance and size are critical.

### Features

- Low Profile − Maximum Height of 1.1 mm
- Small Footprint − Footprint Area of 8.45 $mm^2$
- Low $V_F$ Provides Higher Efficiency and Extends Battery Life
- Supplied in 12 mm Tape and Reel
- Low Thermal Resistance with Direct Thermal Path of Die on Exposed Cathode Heat Sink
- ESD Ratings:
  - ♦ Human Body Model = 3B (> 16 kV)
  - ♦ Machine Model = C (> 400 V)
- AEC−Q101 Qualified and PPAP Capable
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb−Free*

### Mechanical Characteristics:

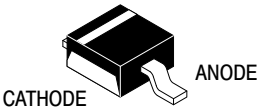
- POWERMITE® is JEDEC Registered as D0−216AA
- Case: Molded Epoxy
- Epoxy Meets UL 94 V−0 @ 0.125 in
- Weight: 16.3 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**ON Semiconductor®**

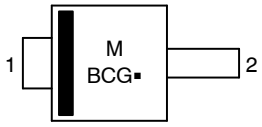
**http://onsemi.com**

**SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES, 30 VOLTS**




**POWERMITE**
**CASE 457**
**PLASTIC**

**MARKING DIAGRAM**




M = Date Code
BCG = Device Code
▪ = Pb−Free Package

**ORDERING INFORMATION**

| Device | Package | Shipping† |
|---|---|---|
| MBRM130LT1G | POWERMITE (Pb−Free) | 3,000 / Tape & Reel |
| NRVBM130LT1G | POWERMITE (Pb−Free) | 3,000 / Tape & Reel |
| MBRM130LT3G | POWERMITE (Pb−Free) | 12,000 / Tape & Reel |
| NRVBM130LT3G | POWERMITE (Pb−Free) | 12,000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---|---|---|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage | $V_{RRM}$<br>$V_{RWM}$<br>$V_R$ | 30 | V |
| Average Rectified Forward Current<br>(At Rated $V_R$, $T_C$ = 135°C) | $I_O$ | 1.0 | A |
| Peak Repetitive Forward Current<br>(At Rated $V_R$, Square Wave, 100 kHz, $T_C$ = 135°C) | $I_{FRM}$ | 2.0 | A |
| Non−Repetitive Peak Surge Current<br>(Non−Repetitive peak surge current, halfwave, single phase, 60 Hz) | $I_{FSM}$ | 50 | A |
| Storage Temperature | $T_{stg}$ | −55 to 150 | °C |
| Operating Junction Temperature | $T_J$ | −55 to 125 | °C |
| Voltage Rate of Change<br>(Rated $V_R$, $T_J$ = 25°C) | dv/dt | 10,000 | V/μs |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

## THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|---|---|---|---|
| Thermal Resistance, Junction−to−Lead (Anode) (Note 1)<br>Thermal Resistance, Junction−to−Tab (Cathode) (Note 1)<br>Thermal Resistance, Junction−to−Ambient (Note 1) | $R_{tjl}$<br>$R_{tjtab}$<br>$R_{tja}$ | 35<br>23<br>277 | °C/W |

1. Mounted with minimum recommended pad size, PC Board FR4, See Figures 9 & 10

## ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Value | | Unit |
|---|---|---|---|---|
| Maximum Instantaneous Forward Voltage (Note 2), See Figure 2 | $V_F$ | **$T_J$ = 25°C** | **$T_J$ = 85°C** | V |
| ($I_F$ = 0.1 A)<br>($I_F$ = 1.0 A)<br>($I_F$ = 3.0 A) | | 0.30<br>0.38<br>0.52 | 0.20<br>0.33<br>0.50 | |
| Maximum Instantaneous Reverse Current (Note 2), See Figure 4 | $I_R$ | **$T_J$ = 25°C** | **$T_J$ = 85°C** | mA |
| ($V_R$ = 30 V)<br>($V_R$ = 20 V)<br>($V_R$ = 10 V) | | 0.41<br>0.13<br>0.05 | 11<br>5.3<br>3.2 | |

2. Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2%

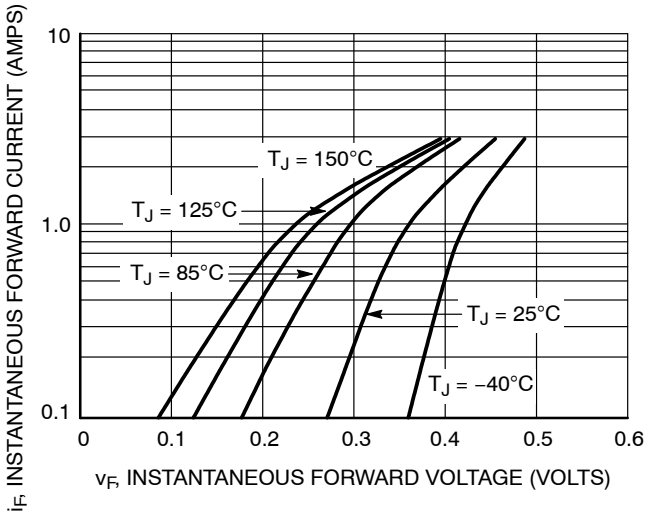



**Figure 1. Typical Forward Voltage**

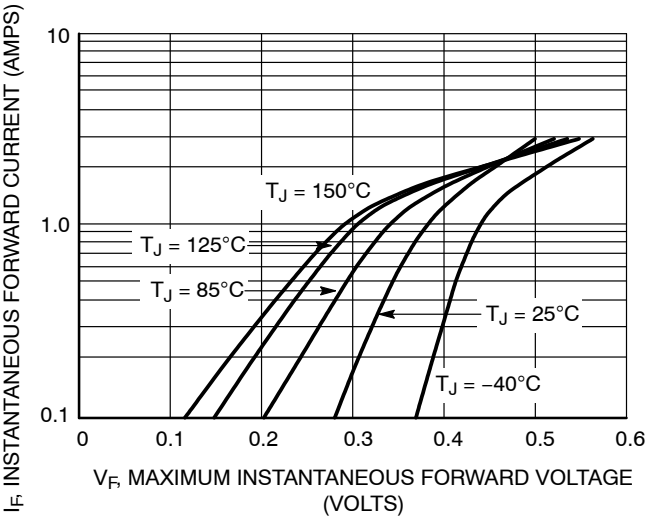



**Figure 2. Maximum Forward Voltage**

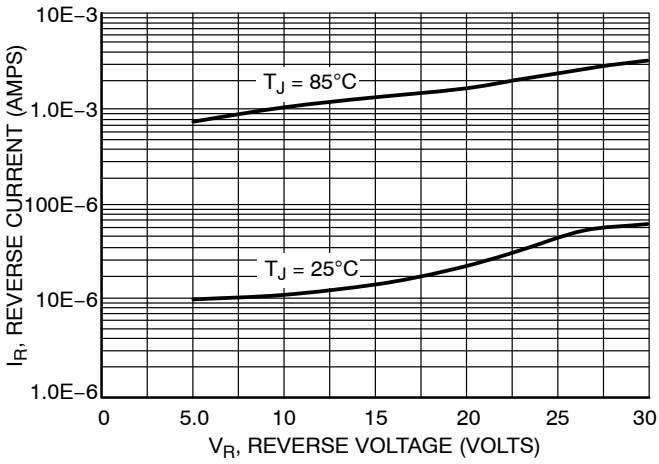



**Figure 3. Typical Reverse Current**

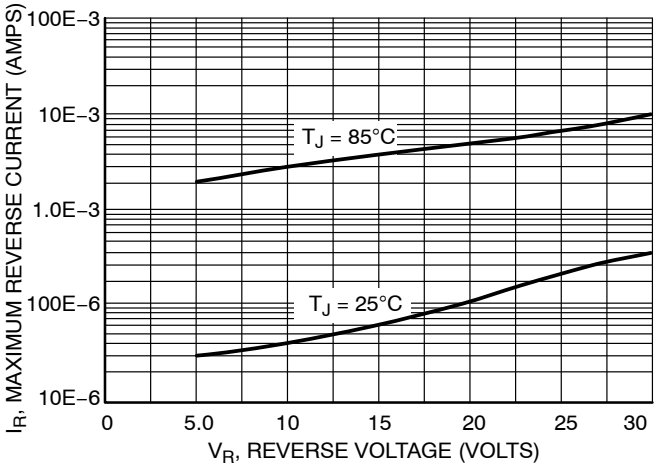



**Figure 4. Maximum Reverse Current**

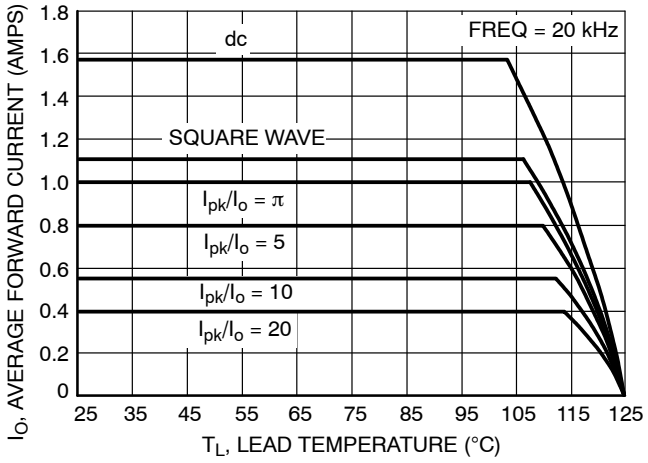



**Figure 5. Current Derating**

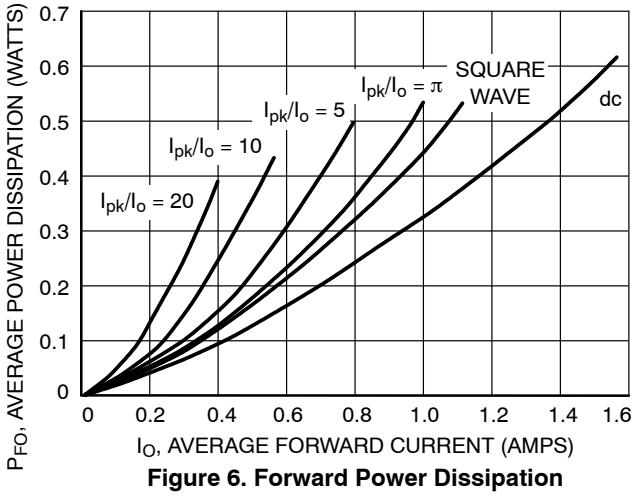



**Figure 6. Forward Power Dissipation**

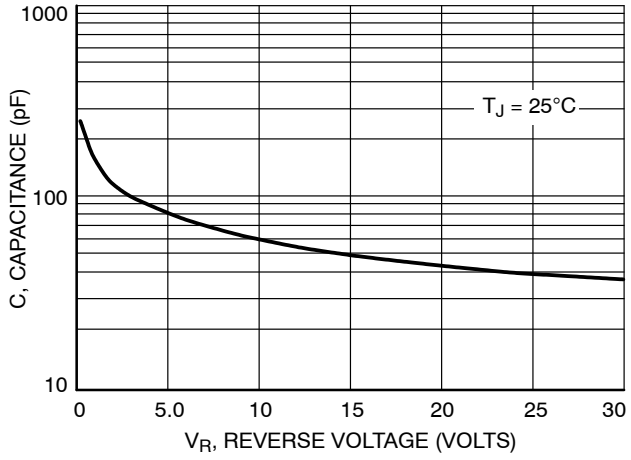



**Figure 7. Capacitance**

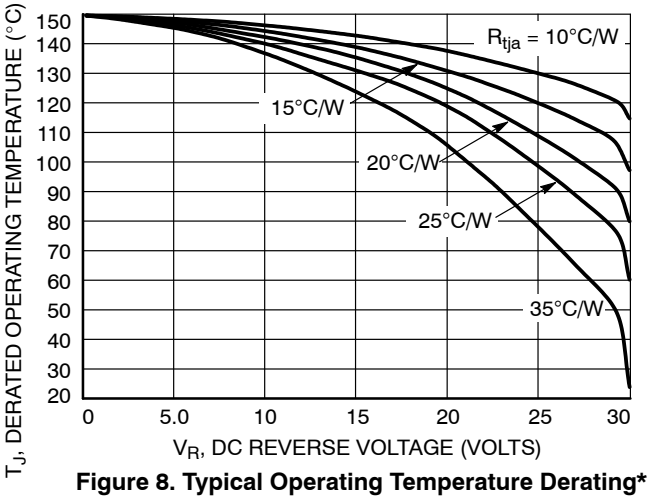



**Figure 8. Typical Operating Temperature Derating***

* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of $T_J$ therefore must include forward and reverse power effects. The allowable operating $T_J$ may be calculated from the equation: $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where

r(t) = thermal impedance under given conditions,
Pf = forward power dissipation, and
Pr = reverse power dissipation

This graph displays the derated allowable $T_J$ due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where r(t) = Rthja. For other power applications further calculations must be performed.

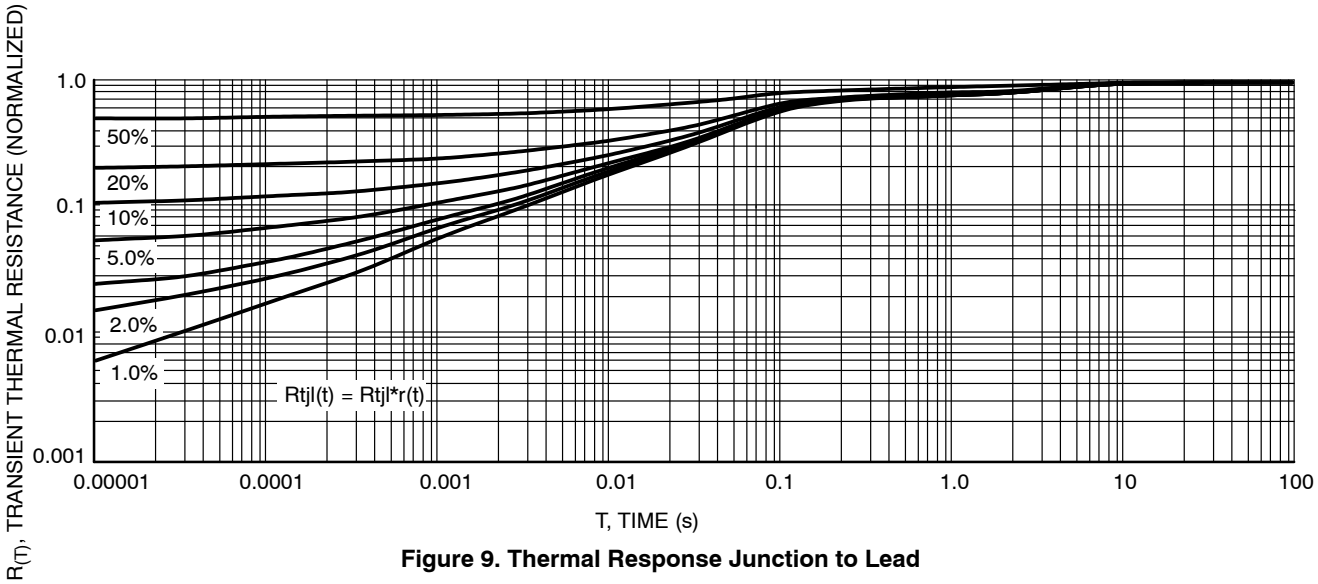



**Figure 9. Thermal Response Junction to Lead**

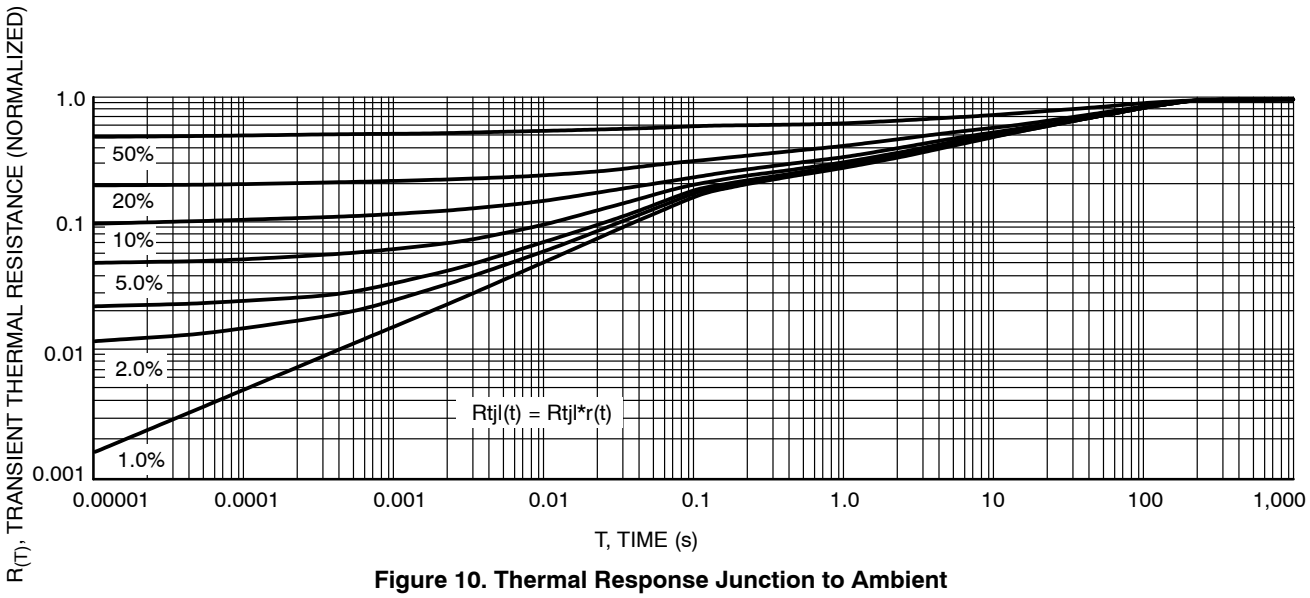



**Figure 10. Thermal Response Junction to Ambient**

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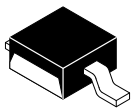
# MECHANICAL CASE OUTLINE
## PACKAGE DIMENSIONS

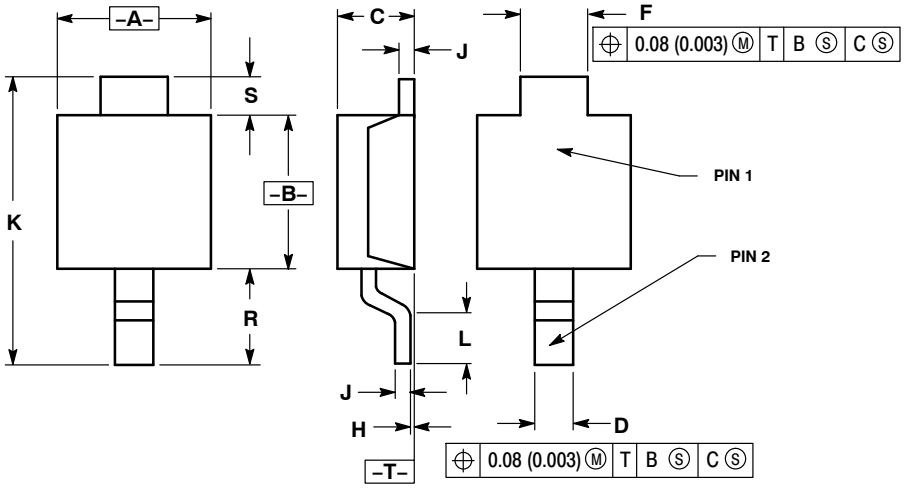
ON Semiconductor®



SCALE 4:1

**POWERMITE**
CASE 457−04
ISSUE F

DATE 14 MAY 2013




NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

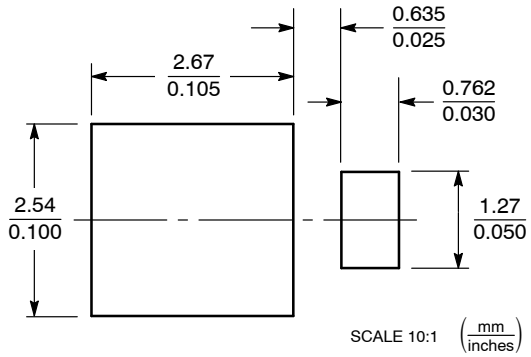
| | MILLIMETERS | | INCHES | |
|---|---|---|---|---|
| DIM | MIN | MAX | MIN | MAX |
| A | 1.75 | 2.05 | 0.069 | 0.081 |
| B | 1.75 | 2.18 | 0.069 | 0.086 |
| C | 0.85 | 1.15 | 0.033 | 0.045 |
| D | 0.40 | 0.69 | 0.016 | 0.027 |
| F | 0.70 | 1.00 | 0.028 | 0.039 |
| H | −0.05 | +0.10 | −0.002 | +0.004 |
| J | 0.10 | 0.25 | 0.004 | 0.010 |
| K | 3.60 | 3.90 | 0.142 | 0.154 |
| L | 0.50 | 0.80 | 0.020 | 0.031 |
| R | 1.20 | 1.50 | 0.047 | 0.059 |
| S | 0.50 REF | | 0.019 REF | |

STYLE 1:
PIN 1. CATHODE
2. ANODE

STYLE 2:
PIN 1. ANODE OR CATHODE
2. CATHODE OR ANODE
(BI−DIRECTIONAL)

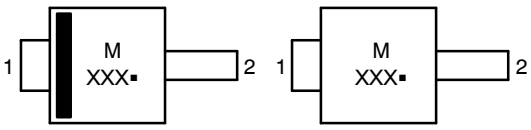
STYLE 3:
PIN 1. ANODE
2. CATHODE

### SOLDERING FOOTPRINT*

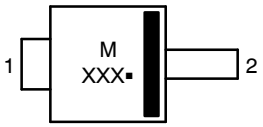



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### GENERIC MARKING DIAGRAMS*




STYLE 1 STYLE 2




STYLE 3

XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

| | | | |
|---|---|---|---|
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